

Schedule at a Glance

Day 1

Keynotes

Poster session (mixed topics)

Day 2

System Integration

Power Modules

Packaging and Manufacturing Processes

Day 3

Dielectrics & Insulation

Thermal Issues

EMI

IWIPP 2021 Keynotes

Packaging for High Voltage

Ty McNutt, Wolfspeed, USA

Paving the Way to Automotive GaN: The Importance of Packaging

Tamara Baksht, ViSiC, Israel

Electrical Topology of a Pure EV: The Porsche Taycan

Thomas Krauss, Porsche, Germany

Environmental Trends and Challenges on Power Packaging

Garron Morris and Chris Genthe, Rockwell Automation, USA

Insulation Materials and Systems for Power Electronic Modules: Challenges and Future Research Needs

Mona Ghassemi, Virginia Tech, USA

Packaging, Integration and Fast switching: what has been achieved and what's next?

Dr. Eckart Hoene, Fraunhofer, Germany